HT82V805 CCD 4 Channel Vertical Driver

Technical Document

- Tools Information
- **FAQs**
- Application Note

Features

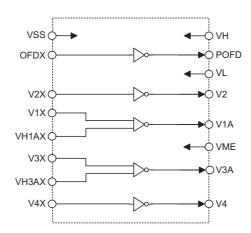
- Input voltage: 3.0V~5.5V
- · Built-in seven circuits
 - 2-level output:
 - 2 circuits for vertical CCD clock driver output voltage level (typ.) = -9V to 0V
 - 3-level output:
 2 circuits for vertical CCD clock driver output voltage level (typ.) = -9V to 15V
- 2-level output:
 1 circuit for shutter driver
 output voltage level (typ.) = -9V to 15V
- Switchable between NTSC (EIA) and PAL (CCIR) modes
- 16-pin SSOP/TSSOP package

General Description

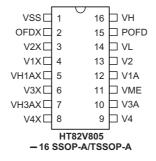
HT82V805 is a CMOS vertical clock driver and shutter driver IC for CCD area sensors. It has the capability of

converting the voltage and impedance from the CMOS

Block Diagram



Pin Assignment



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Pin Description

Pin No.	Pin Name	I/O	Description	
1	VSS	_	Negative power supply, ground	
2	OFDX	I	Electronic shutter pulse input	
4, 3, 6, 8	V1X, V2X, V3X, V4X	I	Vertical transfer pulse input	
5, 7	VH1AX, VH3AX	I	Pulse that transfers the charge of the photo-diode to the vertical shift register.	
9	V4	0	Pulse to drive vertical CCD shift register (2 level: VME, VL)	
10	V3A	0	Pulse to drive vertical CCD shift register (3 level: VME, VL, VH)	
11	VME	_	Power supply for intermediate level of V1A, V3A	
12	V1A	0	Pulse to drive vertical CCD shift register (3 level: VME, VL, VH)	
13	V2	0	Pulse to drive vertical CCD shift register (2 level: VME, VL)	
14	VL	_	Power supply for all low level output pulses	
15	POFD	0	Electronic shutter pulse output (2 level: VL, VH)	
16	VH	_	Power supply for high level of V1A, V3A	

Absolute Maximum Ratings

Supply VoltageV _{SS} -0.3V to V _L +35V	Storage Temperature55°C to 150°C
Input VoltageV _{SS} -0.3V to V _H +0.3V	Operating Temperature25°C to 70°C

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Recommended Operating Conditions

Symbol	Parameter	Value	Unit
V _H		-0.3 ∼ V _L +35	V
V _L	Supply Voltage	0 ~ -10	V
VME		V _L -0.3 ~ 3.0	V
V1A, V2, V3A, V4, POFD	Output Voltage	V _L -0.3 ~ V _H +0.3	V

Logic Function Table

Input					Output	
V1X, V3X	VH1AX, VH3AX	V2X, V4X	OFDX	V1A, V3A	V2, V4	POFD
L	L	_	_	VH	_	_
Н	L	_	_	Z	_	_
L	Н	_	_	VME	_	_
Н	Н	_	_	VL	_	_
	_	L	_	_	VME	_
_	_	Н	_	_	VL	_
_	_	_	L	_	_	VH
	_	<u> </u>	Н	_	_	VL

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D.C. Characteristics

 V_H =15V, V_L =-9V, V_{ME} =0V, Ta=25°C

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V_{DD}	Logic Supply Voltage	_	3.0	3.3	5.5	V
V _H	Supply Voltage	_	14.5	15	15.5	V
V _L	Supply Voltage	_	-9.5	-8.5	-7.5	V
V _{IH}	High Level Input Voltage	_	2.4	_	_	V
V _{IL}	Low Level Input Voltage	_	_	_	1.2	V
I _{VH}			_	3.8	_	mA
I _{VL}	Operating Current	Shutter speed=100kHz	_	-2	_	mA
I _{VME}			_	-6.5	_	mA
I _{OL}		V1A, V2, V3A, V4=-9.0V	_	37	_	mA
I _{OM1}		V1A, V2, V3A, V4=-0.5V	_	-15	_	mA
I _{OM2}	Outside Comment	V1A, V3A=0.5V	_	13.5	_	mA
I _{OH}	Output Current	V1A, V3A=14.5V	_	-18	_	mA
I _{OSL}		OFDX=-8.0V	_	18	_	mA
I _{OSH}		OFDX=14.5V	_	-10.5	_	mA

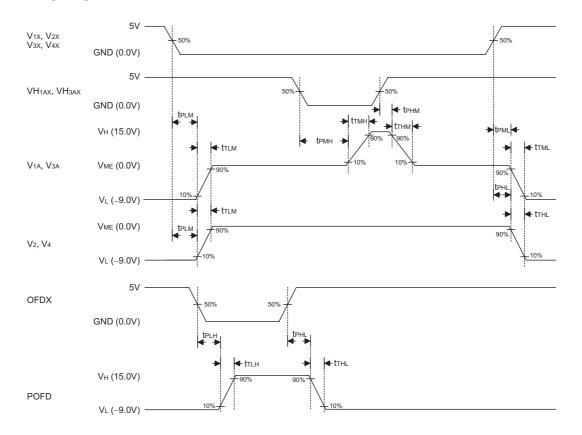
A.C. Characteristics

Ta=25°C

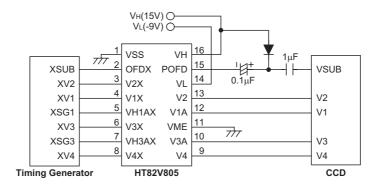
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{PLM}		V _H =15V, V _L =-8.5V, V _{ME} =0V	_	55	80	ns
t _{PMH}		V _H =15V, V _L =-8.5V, V _{ME} =0V	_	50	90	ns
t _{PLH}	Dalau Tima	V _H =15V, V _L =-8.5V, V _{ME} =0V	_	55	100	ns
t _{PML}	Delay Time	V _H =15V, V _L =-8.5V, V _{ME} =0V	_	45	130	ns
t _{PHM}		V _H =15V, V _L =-8.5V, V _{ME} =0V	_	50	120	ns
t _{PHL}		V _H =15V, V _L =-8.5V, V _{ME} =0V	_	55	100	ns
t _{TLM}		V _H =15V, V _L =-8.5V, V _{ME} =0V	_	370	900	ns
t _{TMH}		V _H =15V, V _L =-8.5V, V _{ME} =0V	_	785	900	ns
t _{TLH}	Diain a Time	V _H =15V, V _L =-8.5V, V _{ME} =0V	_	70	140	ns
t _{TML}	Rising Time	V _H =15V, V _L =-8.5V, V _{ME} =0V	_	300	700	ns
t _{THM}		V _H =15V, V _L =-8.5V, V _{ME} =0V	_	630	960	ns
t _{THL}		V _H =15V, V _L =-8.5V, V _{ME} =0V	_	45	120	ns



Timing Diagrams



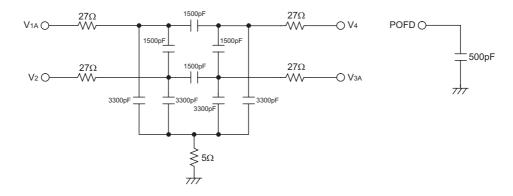
Application Circuits



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Equivalent Circuits

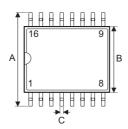


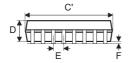
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Package Information

16-pin SSOP (150mil) Outline Dimensions





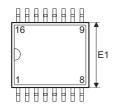


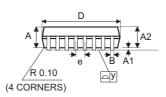
Complete I	Dimensions in mil			
Symbol	Min.	Nom.	Max.	
Α	228	_	244	
В	150	_	157	
С	8	_	12	
C'	189	_	197	
D	54	_	60	
E	_	25	_	
F	4	_	10	
G	22	_	28	
Н	7	_	10	
α	0°	_	8°	

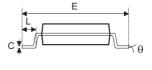
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16-pin TSSOP Outline Dimensions







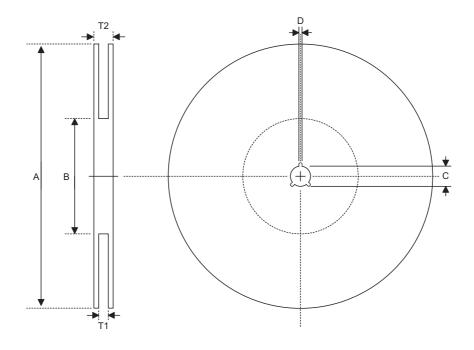
Complete I		Dimensions in mm				
Symbol	Min.	Nom.	Max.			
А	1	_	1.05			
A1	0.05	_	0.15			
A2	1.05	_	1.2			
В		0.25	_			
С	0.11	_	0.15			
D	4.9	_	5.1			
E	6.2	_	6.6			
E1	4.3	_	4.5			
е	_	0.65	_			
L	0.5	_	0.7			
у	_	_	0.076			
θ	0°	_	8°			

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Product Tape and Reel Specifications

Reel Dimensions



SSOP 16S

Symbol	Description	Dimensions in mm
А	Reel Outer Diameter	330±1.0
В	Reel Inner Diameter	62±1.5
С	Spindle Hole Diameter	13.0+0.5 -0.2
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	12.8+0.3 -0.2
T2	Reel Thickness	18.2±0.2

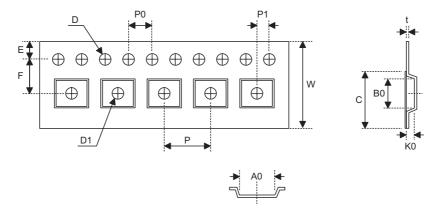
TSSOP 16L

Symbol	Description	Dimensions in mm
А	Reel Outer Diameter	330±1
В	Reel Inner Diameter	62±1.5
С	Spindle Hole Diameter	13+0.5 -0.2
D	Key Slit Width	2±0.5
T1	Space Between Flange	16.8+0.3 -0.2
T2	Reel Thickness	22.2±0.2

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Carrier Tape Dimensions



SSOP 16S

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	12.0+0.3 -0.1
Р	Cavity Pitch	8.0±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	5.5±0.1
D	Perforation Diameter	1.55±0.1
D1	Cavity Hole Diameter	1.5+0.25
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	6.4±0.1
В0	Cavity Width	5.2±0.1
K0	Cavity Depth	2.1±0.1
t	Carrier Tape Thickness	0.30±0.05
С	Cover Tape Width	9.3

TSSOP 16L

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	16+0.3 -0.1
Р	Cavity Pitch	8±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	7.5±0.5
D	Perforation Diameter	1.5+0.1
D1	Cavity Hole Diameter	1.5+0.1
P0	Perforation Pitch	4±0.1
P1	Cavity to Perforation (Length Direction)	2±0.1
A0	Cavity Length	6.8±0.1
B0	Cavity Width	5.4±0.1
K0	Cavity Depth	1.6±0.1
t	Carrier Tape Thickness	0.3±0.013
С	Cover Tape Width	13.3

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